

IN THE CLAIMS:

Claims 1 through 7, 22, and 23 were previously cancelled. Claims 9 and 14 have been amended herein. All of the pending claims are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

Listing of Claims:

1.-7. (Cancelled)

8. (Previously presented) An electronic device package comprising:
a transparent substrate;
a plurality of conductive traces positioned on a surface of the transparent substrate, each
conductive trace of the plurality of conductive traces having a first attachment point and a
second attachment point;
a plurality of optically interactive electronic devices, each optically interactive electronic device
having at least one bond pad and mounted to the transparent substrate by a bond between
the first attachment point of an associated conductive trace of the plurality of conductive
traces and the at least one bond pad;
a plurality of backing caps, each backing cap covering a back surface of each optically interactive
electronic device and having at least one backing cap attachment point on a surface
thereof in electrical communication with the second attachment point of the associated
conductive trace and at least one attachment pad on another surface of the backing cap in
electrical communication with the at least one backing cap attachment point.

9. (Currently amended) An electronic device package comprising:
a transparent substrate;
at least one secondary substrate secured by a first surface thereof to a surface of the transparent substrate having a central aperture covered by the transparent substrate and a plurality of conductive traces positioned on the at least one secondary substrate around the central aperture, each conductive trace of the plurality of conductive traces having a first attachment point and a second attachment point on a second surface of the at least one secondary substrate;
an optically interactive electronic device having at least one bond pad, the optically interactive electronic device mounted to the at least one secondary substrate by a bond between the first attachment point of a conductive trace of the plurality of conductive traces and the at least one bond pad; and
a backing cap covering a back surface of the optically interactive electronic device, the backing cap having at least one backing cap attachment point on a surface thereof in electrical communication with the second attachment point of the conductive trace and at least one attachment pad on another surface of the backing cap in electrical communication with the at least one backing cap attachment point.

10. (Original) The electronic device package according to claim 9, further comprising:
a bond between the at least one backing cap attachment point and the second attachment point of the conductive trace, the bond comprising one of a conductive or conductor-filled epoxy, a solder joint and a layer of anisotropically conductive adhesive material.

11. (Previously presented) The electronic device package according to claim 9, further comprising:
an array of attachment pads on the another surface of the backing cap, the array of attachment pads positioned adjacent four edges of an outer perimeter of the another surface of the backing cap.

12. (Previously presented) The electronic device package according to claim 9, further comprising:
a discrete conductive element disposed on the at least one attachment pad on the another surface of the backing cap.

13. (Original) The electronic device package according to claim 12, wherein the discrete conductive element comprises one of a solder ball, a solder column, a conductive epoxy, and a conductor-filled epoxy.

14. (Currently amended) The electronic device package according to claim 9, wherein the at least one secondary substrate comprises one of a printed circuit board, a polyimide film, a ceramic, and silicon.

15. (Previously presented) The electronic device package according to claim 9, wherein an outside perimeter of the at least one secondary substrate is substantially equal to an outside perimeter of the transparent substrate.

16. (Original) The electronic device package according to claim 9, wherein the optically interactive electronic device comprises an image sensor.

17. (Previously presented) The electronic device package according to claim 9, wherein the at least one secondary substrate comprises a plurality of secondary substrates, each secondary substrate of the plurality secured to the surface of the transparent substrate, and the at least one optically interactive device comprises a plurality of optically interactive devices.

18. (Previously presented) The electronic device package according to claim 8, further comprising:
a bond between the at least one backing cap attachment point and the second attachment point of the associated conductive trace, the bond comprising one of a conductive or conductor-filled epoxy, a solder joint and a layer of anisotropically conductive adhesive material.

19. (Previously presented) The electronic device package according to claim 8, further comprising:
an array of attachment pads on the another surface of the backing cap, the array of attachment pads positioned adjacent four edges of an outer perimeter of the another surface of the backing cap.

20. (Previously presented) The electronic device package according to claim 8, further comprising:
a discrete conductive element disposed on the at least one attachment pad on the another surface of the backing cap.

21. (Previously presented) The electronic device package according to claim 20, wherein the discrete conductive element comprises one of a solder ball, a solder column, a conductive epoxy, and a conductor-filled epoxy.

22. (Cancelled)

23. (Cancelled)

24. (Previously presented) The electronic device package according to claim 8, wherein the plurality of optically interactive electronic devices comprise a plurality of image sensors.